### **Conformal Coating**



# ELAN-*Tron*<sup>®</sup>, ELAN-*Cast*<sup>®</sup>, and Bectron<sup>®</sup> resins for Conformal Coating



A member of **C ALTANA** 

## Conformal Coatings

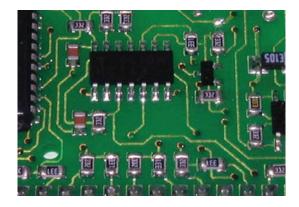
### **Product Summary**

ELAN-*Tron*<sup>®</sup>, ELAN-*Cast*<sup>®</sup>, and Bectron<sup>®</sup> conformal coatings are designed for easy dip or spray application to printed circuit boards.

#### **Product Uses**

- Printed Circuit Boards
- Surface Mount Devices







## **Application Methods**

• Spray • Dip



Mix

Cure Schedule

Maximum

Service

<b>Product Characteristics</b>	
at a Glance	

ELAN-Tron® C 126 Hardener system. Low heat cure. Slightly thixotropic for thick film build. Dip application. (mixed)   ELAN-Cast® E 471-5LL FR Black Resin Two-component, filled epoxy resin system for thick film build. UI System listed Flame 2000 - 3000 10	Ratio		for Optimum Properties	Service Temperature (IEC 60085)	Solids Content
Image: Provide the second s	-		30 m at 25°C	85°C	21.0%
alkyd resin system for thin film build. Room temperature or accelerated cure up to 80°C. UV tracer. Formulated for air-assisted spray application. UL 94 V0 listed. Temperature index 134°C per IEC 60216. This coating is IPC-CC- 830 2002 Class A qualified.   Bectron® PL 4122-40 E BLF FLZ Clear, single-component, urethane-modified alkyd resin system for thin film build. Room temperature or accelerated cure up to 80°C. UV tracer. A122-40 E for airless spray application, 4122-45 E bl.F FLZ 60 - 100 200 - 300   Bectron® PL 4122-45 E BLF FLZ Clear, single-component, urethane-modified alkyd resin system for thin film build. Room temperature index 134°C per IEC 60216. This coating is IPC-CC-830 2002 Class A qualified. 60 - 100 200 - 300   Bectron® PT 4600 Clear, single-component, thick film polyurethane resin system. UV / moisture cure. 500 - 1500   Bectron® MR 3406 A modified polyolefin hot melt for use as a thick film coating in electronic protection. Environmentally friendly containing no solvents and zero VOCs. Offres excellent electrical insulation properties, protection against humidity and good chemical resistance. Suitable for application by hand with a hot-melt dispensing. Coating can be easily reworked or repaired. 4500 - 6500   Bectron® PK 4332 Black single-component, very flexible polyurethane resin system. For selective coating of SMD and other sensitive components on printed circuit boards. Excellent thermal cycling performance from - 60°C to +125°C. Thick film build depending on application mode. 4500 - 7500 (mixed) 10   ELAN-Tron® C 126 Hardener Two-component, filled epoxy resin system. Low heat cure. Slightl	-	-	30 m at 25°C	85°C	20.5%
Bectron® PL 4122-45 E BLF FLZ alkyd resin system for thin film build. Room temperature or accelerated cure up to 80°C. UV tracer. 4122-40 E for airless syray application, 4122-45 E for dip application. UL 94 V0 listed. Temperature index 134°C per IEC 60216. This coating is IPC-CC-830 2002 Class A qualified. 200 - 300   Bectron® PT 4600 Clear, single-component, thick film polyurethane resin system. UV / moisture cure. 500 - 1500   Bectron® MR 3406 A modified polyolefin hot melt for use as a thick film coating in electronic protection. Environmentally friendly containing no solvents and zero VOCs. Offers excellent electrical insulation properties, protection against humidity and good chemical resistance. Suitable for application by hand with a hot-melt gun or, with modifications, by automated dispensing. Coating can be easily reworked or repaired. 4500 - 6500   Bectron® PK 4332 Black single-component, unfilled epoxy resin system. For selective coating of SMD and other sensitive components on printed circuit boards. Excellent thermal cycling performance from - 60°C to +125°C. Thick film build depending on application mode. 4500 - 7500 (mixed)   ELAN-Tron® C 126 Hardener Clear, two-component, unfilled epoxy resin system. Low heat cure. Slightly thixotropic for thick film build. Dip application. 2000 - 3000 10   ELAN-Cast® E 471-5LL FR Black Resin ELAN-Cast® E 471-5LL FR Black Resin Two-component, filled epoxy resin system for thick film build. U. System listed. Flame 2000 - 3000 10	-	•	16 h at 25°C or 0.75 h at 80°C	130°C	40%
polyurethane resin system. UV / moisture cure.   Bectron® MR 3406 A modified polyolefin hot melt for use as a thick film coating in electronic protection. Environmentally friendly containing no solvents and zero VOCs. Offers excellent electrical insulation properties, protection against humidity and good chemical resistance. Suitable for application by hand with a hot-melt gun or, with modifications, by automated dispensing. Coating can be easily reworked or repaired. 4500 - 6500   Bectron® PK 4332 Black single-component, very flexible polyurethane resin system. For selective coating of SMD and other sensitive components on printed circuit boards. Excellent thermal cycling performance from - 60°C to +125°C. Thick film build depending on application mode. 4500 - 7500 (mixed)   ELAN-Tron® E 697 Resin ELAN-Tron® C 126 Hardener Clear, two-component, unfilled epoxy resin system for thick film build. Dip application. 4500 - 7500 (mixed) 10 (mixed)   ELAN-Cast® E 471-5LL FR Black Resin ELAN-Cast® E 471-5LL FR Black Resin Two-component, filled epoxy resin system for thick film build. U System listed. Flame reardant per UL 94 V0. Enhanced chemical 2000 - 3000 10 (mixed)	-	-	16 h at 25°C or 0.5 h at 80°C	130°C 130°C	40% 45%
Becknon mit 0400 film coating in electronic protection. Environmentally friendly containing no solvents and zero VOCs. Offers excellent electrical insulation properties, protection against humidity and good chemical resistance. Suitable for application by hand with a hot-melt gun or, with modifications, by automated dispensing. Coating can be easily reworked or repaired. (at application temperature)   Bectron® PK 4332 Black single-component, very flexible polyurethane resin system. For selective coating of SMD and other sensitive components on printed circuit boards. Excellent thermal cycling performance from - 60°C to +125°C. Thick film build depending on application mode. 4500 - 6500   ELAN-Tron® E 697 Resin ELAN-Tron® C 126 Hardener Clear, two-component, unfilled epoxy resin system. Low heat cure. Slightly thixotropic for thick film build. Dip application. 4500 - 7500 (mixed) 100 (mixed)   ELAN-Cast® E 471-5LL FR Black Resin ELAN-Cast® E 471-5LLHY FR Black Resin Two-component, filled epoxy resin system for thick film build. UL System listed. Flame retardant per UL 94 V0. Enhanced chemical 2000 - 3000 27000 - 33000 100	-	- (	UV light: 5-10 s or 72 h at 25°C	120°C	100%
polyurethane resin system. For selective coating of SMD and other sensitive components on printed circuit boards. Excellent thermal cycling performance from - 60°C to +125°C. Thick film build depending on application mode. 4500 - 7500 (mixed)   ELAN-Tron® E 697 Resin ELAN-Tron® C 126 Hardener Clear, two-component, unfilled epoxy resin system. Component, unfilled epoxy resin system. Low heat cure. Slightly thixotropic for thick film build. Dip application. 4500 - 7500 (mixed) 100 (mixed)   ELAN-Cast® E 471-5LL FR Black Resin ELAN-Cast® E 471-5LLHY FR Black Resin Two-component, filled epoxy resin system for thick film build. UL System listed. Flame retardant per UL 94 V0. Enhanced chemical 2000 - 33000 (no) 100 (mixed)	-	-	190°C (application temperature)	130°C	100%
ELAN-Tron® C 126 Hardener system. Low heat cure. Slightly thixotropic for thick film build. Dip application. (mixed)   ELAN-Cast® E 471-5LL FR Black Resin ELAN-Cast® E 471-5LLHV FR Black Resin Etardant per UL 94 V0. Enhanced chemical Two-component, filled epoxy resin system for thick film build. UL System listed. Flame retardant per UL 94 V0. Enhanced chemical 2000 - 3000 10	-	- 7	70-90 m at 90°C	130°C	100%
ELAN-Cast <sup>®</sup> E 471-5LLHV FR Black Resin thick film build. UL System listed. Flame retardant per UL 94 V0. Enhanced chemical 27000 - 33000 10	100:50	100:50	4 h at 65°C	155°C	97%
ELAN-Cast® C 471-5LL Hardener low heat cure schedule may be possible for your application. Consult	100:15 100:15	100:15	168 h at 25°C or 4 h at 80°C	130°C	100%

Alternate cure schedule may be possible for your application. Consult with your ELANTAS PDG representative.

For More Information Ask For Our Technical Data Sheets.

## **ELANTAS PDG, Inc.**

#### **ELANTAS Electrical Insulation**

Around the world, ELANTAS Electrical Insulation companies are respected as market leaders in the development and manufacturing of impregnating resins (varnishes), wire enamel, potting compounds and casting resins for a number of electrical, industrial, aerospace and civil applications. No matter what your challenge, be assured that ELANTAS Electrical Insulation products will meet your most demanding needs.

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Today, ELANTAS PDG, Inc. is recognized as the premier global supplier of specialty polymers for the electrical and electronic industries. ELANTAS PDG, Inc. is a member of ALTANA's ELANTAS Electrical Insulation Division based in Wesel, Germany.

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Many ELANTAS PDG, Inc. products are recognized as components of electrical insulation systems in accordance with UL 1446. ELANTAS PDG, Inc. is registered to ISO 9001 and ISO/TS 16949.

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ELANTAS PDG, Inc. headquarters in St. Louis, Missouri

ELANTAS Electrical Insulation companies are strategically located throughout the world to meet the primary insulation, secondary insulation and electronic and engineering materials needs of our customers.

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